

SWITCHING

P-CHANNEL POWER MOSFET

DESCRIPTION

The μ PA2733GR is P-channel MOS Field Effect Transistor designed for power management applications of notebook computers and so on.

FEATURES

- Low on-state resistance
 $R_{DS(on)1} = 38 \text{ m}\Omega \text{ MAX. (} V_{GS} = -10 \text{ V, } I_D = -2.5 \text{ A)}$
 $R_{DS(on)2} = 53 \text{ m}\Omega \text{ MAX. (} V_{GS} = -4.5 \text{ V, } I_D = -2.5 \text{ A)}$
- Low C_{iss} : $C_{iss} = 870 \text{ pF TYP.}$
- Built-in gate protection diode
- Small and surface mount package (Power SOP8)

ORDERING INFORMATION

PART NUMBER	PACKAGE
μ PA2733GR-E1	Power SOP8
μ PA2733GR-E1-A ^{Note}	Power SOP8
μ PA2733GR-E2	Power SOP8
μ PA2733GR-E2-A ^{Note}	Power SOP8

Note Pb-free (This product does not contain Pb in external electrode and other parts.)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, All terminals are connected.)

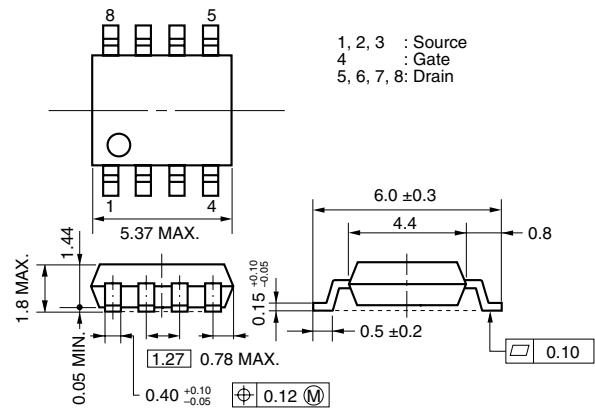
Drain to Source Voltage ($V_{GS} = 0 \text{ V}$)	V_{DSS}	-30	V
Gate to Source Voltage ($V_{DS} = 0 \text{ V}$)	V_{GSS}	∓ 20	V
Drain Current (DC)	$I_{D(DC)}$	∓ 5	A
Drain Current (pulse) ^{Note1}	$I_{D(pulse)}$	∓ 20	A
Total Power Dissipation ^{Note2}	P_{T1}	1.1	W
Total Power Dissipation (PW = 10 sec) ^{Note2}	P_{T2}	2.5	W
Channel Temperature	T_{ch}	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Notes 1. $PW \leq 10 \mu\text{s}$, Duty Cycle $\leq 1\%$

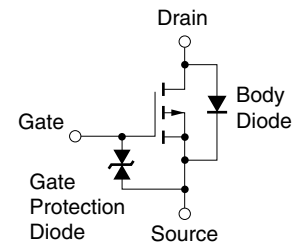
2. Mounted on glass epoxy board of 1 inch x 1 inch x 0.8 mm

Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

PACKAGE DRAWING (Unit: mm)



EQUIVALENT CIRCUIT



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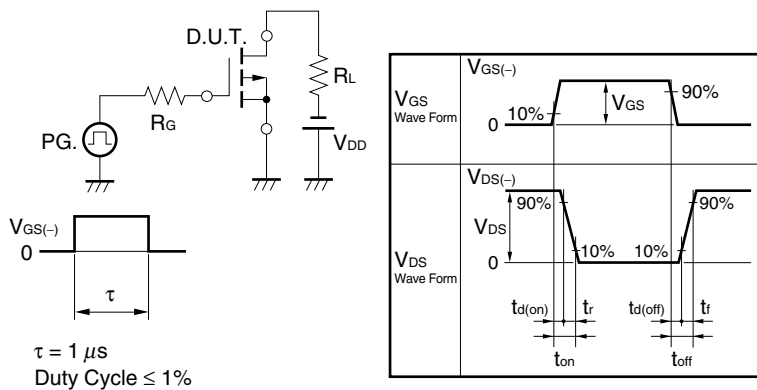
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ELECTRICAL CHARACTERISTICS (T_A = 25°C, All terminals are connected.)

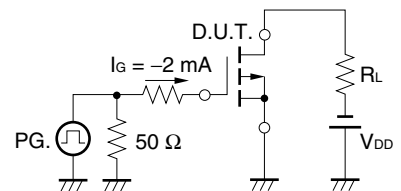
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V			-1	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±20 V, V _{DS} = 0 V			±10	μA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = -10 V, I _D = -1 mA	-1.0		-2.5	V
Forward Transfer Admittance ^{Note}	y _{fs}	V _{DS} = -10 V, I _D = -2.5 A	2.5			S
Drain to Source On-state Resistance ^{Note}	R _{DS(on)1}	V _{GS} = -10 V, I _D = -2.5 A		30	38	mΩ
	R _{DS(on)2}	V _{GS} = -4.5 V, I _D = -2.5 A		39	53	mΩ
Input Capacitance	C _{iss}	V _{DS} = -10 V		870		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V		200		pF
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		150		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = -15 V, I _D = -2.5 A		7.7		ns
Rise Time	t _r	V _{GS} = -10 V		9.5		ns
Turn-off Delay Time	t _{d(off)}	R _G = 10 Ω		108		ns
Fall Time	t _f			64		ns
Total Gate Charge	Q _G	V _{DD} = -24 V		18		nC
Gate to Source Charge	Q _{GS}	V _{GS} = -10 V		2.6		nC
Gate to Drain Charge	Q _{GD}	I _D = -5 A		5.8		nC
Body Diode Forward Voltage ^{Note}	V _{F(S-D)}	I _F = 5 A, V _{GS} = 0 V		0.8		V
Reverse Recovery Time	t _{rr}	I _F = 5 A, V _{GS} = 0 V		98		ns
Reverse Recovery Charge	Q _{rr}	di/dt = 100 A/μs		93		nC

Note Pulsed

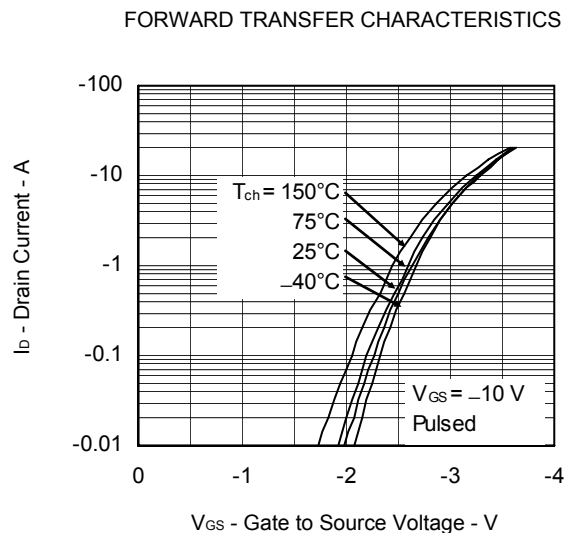
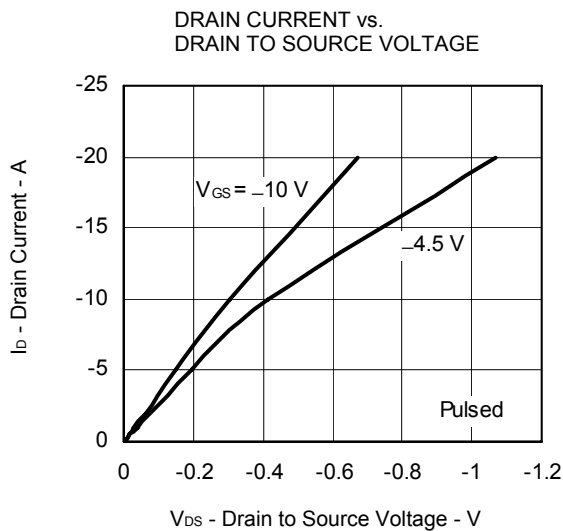
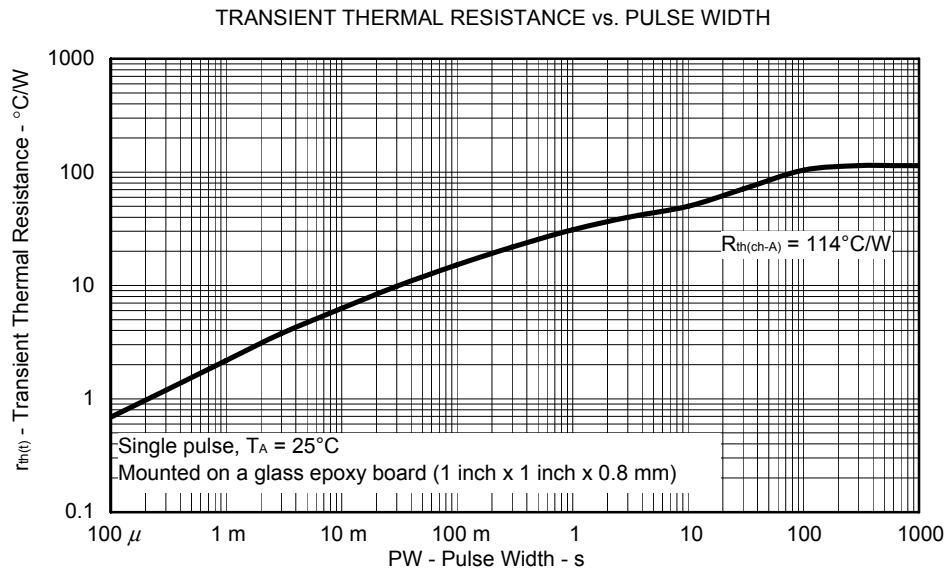
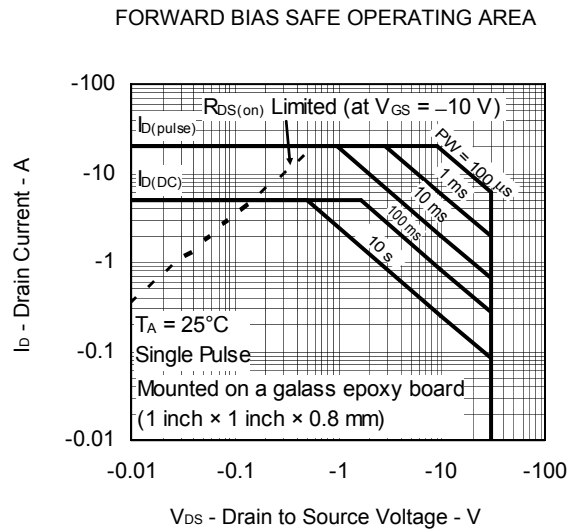
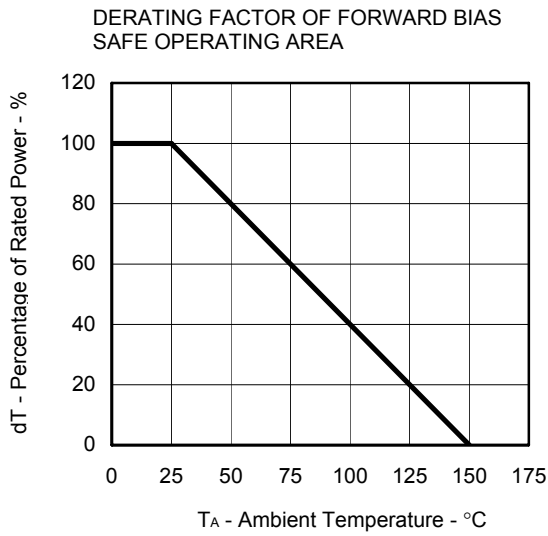
TEST CIRCUIT 1 SWITCHING TIME



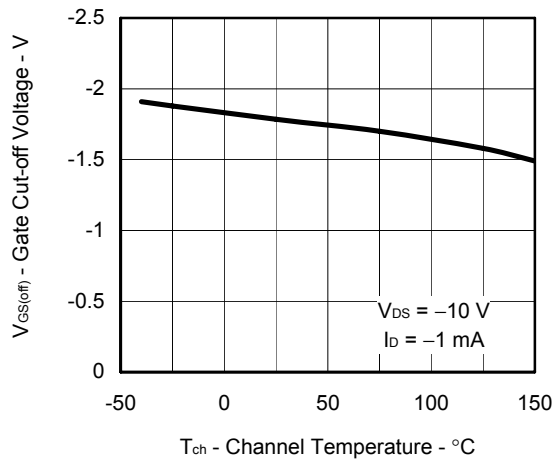
TEST CIRCUIT 2 GATE CHARGE



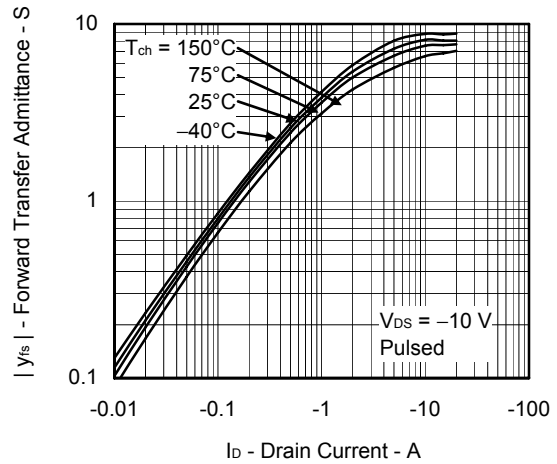
<R> TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)



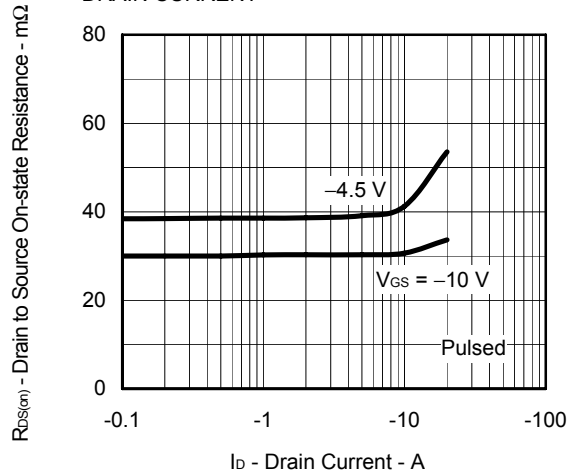
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



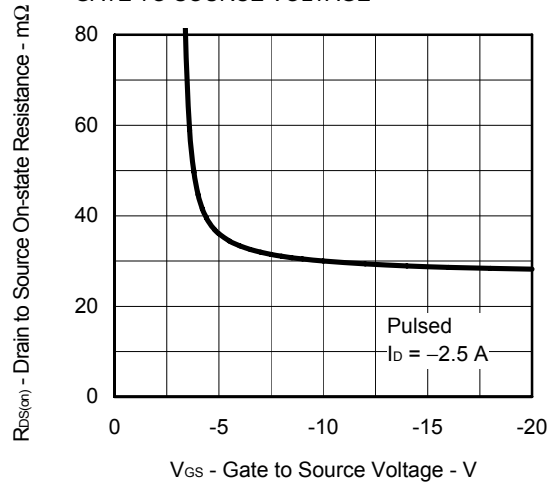
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



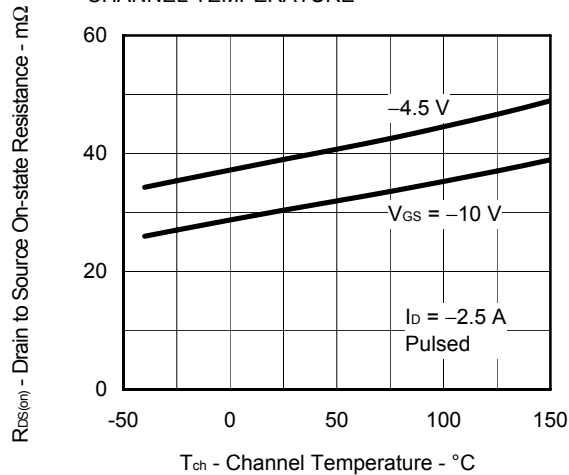
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



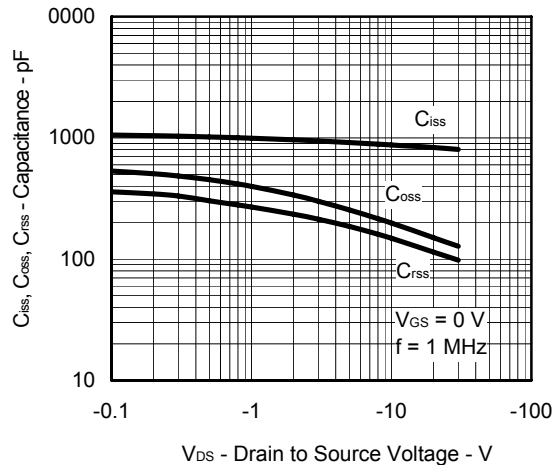
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



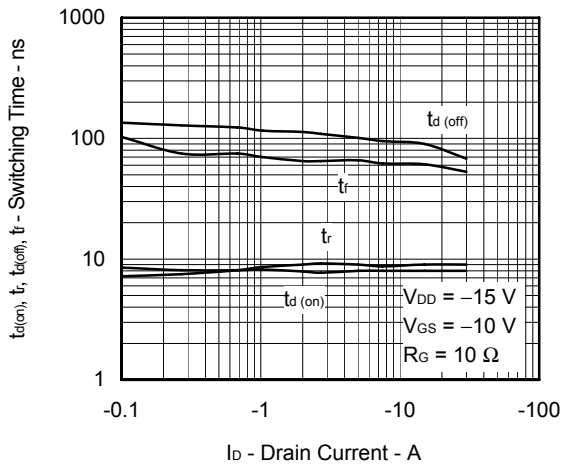
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



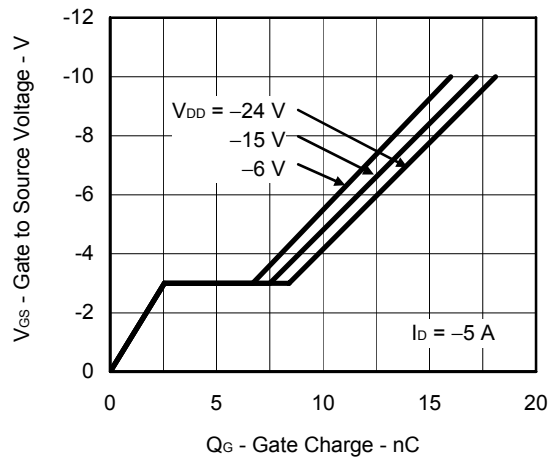
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



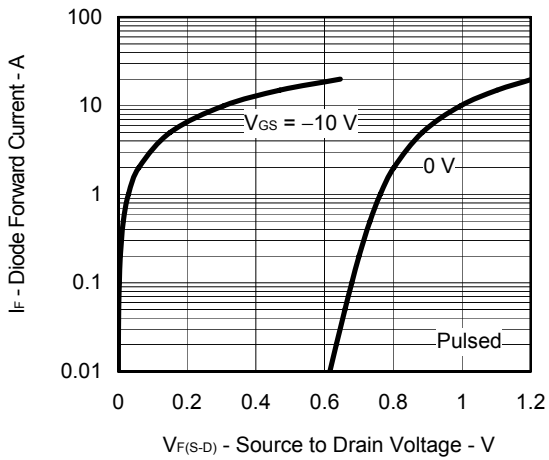
SWITCHING CHARACTERISTICS



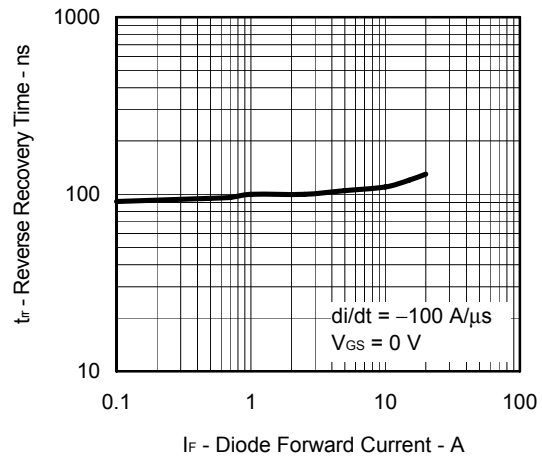
DYNAMIC INPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE



REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



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